

Title (en)

DEVICE FOR FIXING AN ELECTRONIC COMPONENT TO A CARRIER BY MEANS OF A CONDUCTIVE REFRACTORY METAL-GLASS PASTE

Title (de)

EINRICHTUNG ZUR FIXIERUNG EINES ELEKTRONISCHEN BAUSTEINS AUF EINEM TRÄGER MITTELS EINER LEITFÄHIGEN HOCHSCHMELZENDEN METALL-GLAS- PASTE

Title (fr)

DISPOSITIF POUR IMMOBILISER UN COMPOSANT ÉLECTRONIQUE SUR UN SUPPORT AU MOYEN D UNE PÂTE CONDUCTRICE MÉTAL-VERRE À POINT DE FUSION ÉLEVÉ

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Application

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Abstract (en)

[origin: WO2009100797A1] The invention relates to a device for fixing and/or attaching an electronic component such as a semiconductor element (1), and the electroconductive connection thereof to strip conductors, to a carrier (2), by means of a fixing element or a fixing means (3). The fixing element or means (3) is designed such that it maintains its fixing properties at operating temperatures of up to at least 500 °C, and the electronic component is placed on the carrier (2) by means of a paste (3) containing Ag, and fixed or rigidly connected to said carrier. The paste (3) preferably comprises a glass part of between 5 vol % and 25 vol %, especially between 10 vol % and 15 vol %, in relation to the solid part, which melts at a baking temperature of approx. = 600 °C, and wets the surface of the carrier at certain points, thereby creating adhesion points to which the sintered metal, such as Ag, adheres or sticks.

IPC 8 full level

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